

This invention provides / a light-emitting diode which permits mass production and $\!\!/\!\!/$ dense packing into a pattern based on the use of a reflow furnace. Its reflection mirror 15 is obtained by stamping a metal plate to give it a smooth concave shape, $\frac{1}{n}$ and treating its concave surface by plating or depositing, f or example, silver. The reflection mirror 15 is placed in $/\!\!/$ an opposing relation to the lightemitting surface of a / light-emitting element 11; is shaped like approximately a $/\!\!/$ paraboloid of revolution; and has a focal point at which the center of the light emitting surface of light-em $^{/\!\!/}_{m}$ tting element 11 is disposed. The light-emitting element 11, parts of lead assemblies 12a and 12b, a bonding wi#e 13 and the reflection mirror 15 is integrally sealed $\!\!\!/\!\!\!/$ with a light transmissible material 14 by transfer molding The surface of the light transmissible material 14 at #he rear of the light-emitting element serves as a rad/iation surface 21.

(Fig. 2)